



30th Anniversary of the Rencontres du Vietnam



WINDOWS ON THE UNIVERSE

Novel perspectives in radiation detectors for present and future high energy physics experiments



August 11th, 2023



Nobel Prizes: Detection Methods





- 1927: cloud chamber (C.T.R. Wilson)
- 1948: advanced cloud chamber (P.M.S. Blackett)
- 1950: nuclear emulsion (C.F. Powell)
- 1954: coincidence method (W. Bothe)
- 1958: Cherenkov effect (P.A. Cherenkov)
- 1960: bubble chamber (D.A. Glaser)
- 1992: multiwire proportional chamber (G. Charpak)
- 2009: CCD sensor (W.S. Boyle, G.E. Smith)



The Large Hadron Collider (LHC)





- 27 km in circumference
- About 100 m
 underground
- Superconducting magnets steer the particles around the ring
- Particles are accelerated to close to the speed of light
- Collision energy (13) 14TeV



Tools of the trade..



- We build the largest machines to study the smallest particles in the universe
- We develop technology to advance the limits of what is possible





The LHC detectors are analogous to 3D cameras





The detectors measure the energy, direction and charge of new particles formed. They take 40 million pictures a second. Only 1000 are recorded and stored. The LHC detectors have been built by international collaborations covering all regions of the Globe.



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Compact Muon Solenoid









Nobel Prize 2013





ATLAS Experiment





ATLAS facts:

- * Length: 45 m, height: 25 m
- * Weight: 7000 metric tons
- * 150 million electronics channels



Compact integration





Applicable to complex, confined and/or harsh environments, where multiple aspects and diverse technologies need an holistic design approach in order to be integrated into one system.





 History of multifunctional design of systems incorporating a broad range of technologies in small volumes:

$\rightarrow\,$ Ultra-compact integration of complex systems

• Functional analysis capabilities to facilitate holistic design approach across large systems:

→ Optimise ratio between core and auxiliaries services



Compact integration





Experiments running around and outside the LHC are extremely complex and large structures

Main challenge is to maximize the volume dedicated to the detector itself minimizing the volume for auxiliaries services integration of technologies is key.

- Integrate several tons of materials for the detectors in confined area with their own specific constraints:
 - Cooling systems (from ambient down to -35°C)
 - Power cables (total FE electronics power in CMS 1MWatt)
 - Front-end and readout electronics (voltage supply, voltage operation, power consumption)
 - Optical fibres (same length for every single fibre for timing)
- Integrate detector control systems and detector safety systems
- Coordination on sub-detectors from institutes all around the world



Compact integration

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Front and and readout electronics

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Upgrade to the High-Luminosity LHC is under way

The HL-LHC will use new technologies to provide 10 times more collisions than the LHC.

It will provide greater precision and discovery potential.

It will start operating in

Gaseous Detectors @ CMS, ALICE, LHCb Upgrades

Experiment / Timescale	Application Domain	Gas Detector Technology	Total detector size / Single module size	Operation Characteristics / Performance	Special Requirements / Remarks
ALICE TPC UPGRADE CERN LS2	Heavy-Ion Physics (Tracking + dE/dx)	4-GEM / TPC	Total area: ~ 32 m ² Single unit detect: up to 0.3m ²	Max.rate:100 kHz/cm ² Spatial res.: ~300µm Time res.: ~ 100 ns dE/dx: 11 % Rad. Hard.: 50 mC/cm ²	 - 50 kHz Pb-Pb rate; - Continues TPC readout - Low IBF and good energy resolution
CMS MUON UPGRADE GE11 CERN LS2	Hadron Collider (Tracking/Triggering)	3-GEM	Total area: ~ 50 m ² Single unit detect: 0.3-0.4m ²	Max. rate: 5 kHz/cm ² Spatial res.: 0.6 – 1.2mm Time res.: ~ 7 ns Rad. Hard.: ~ 0.18 C/cm ²	Redundant tracking and triggering, improved pt resolution in trigger
CMS MUON UPGRADE GE21 CERN L3	Hadron Collider (Tracking/Triggering)	3-GEM	Total area: ~ 105 m ² Single unit detect: 0.3-0.4m ²	Max. rate: 1.5 kHz/cm ² Spatial res.: 1.4 – 3.0mm Time res.: ~ 7 ns Rad. Hard.: ~ 0.09 C/cm ²	Redundant tracking and triggering, displaced muon triggering
CMS MUON UPGRADE ME0 CERN L3	Hadron Collider (Tracking/Triggering)	3-GEM	Total area: ~ 65 m ² Single unit detect: 0.3m ²	Max. rate:150 kHz/cm ² Spatial res.: 0.6 – 1.3mm Time res.: ~ 7 ns Rad. Hard.: ~ 7.9 C/cm ²	Extension of the Muon System in pseudorapidity, installation behind HGCAL
CMS MUON UPGRADE RE3.1, RE 4.1 2023-24 (CERN L3)	Hadron Collider (Tracking/Triggering)	iRPC	Total area: ~ 140 m ² Single unit detect: 2m ²	Max.rate: 2kHz/cm ² Spatial res.: ~1-2cm Time res.: ~ 1 ns Rad. Hard.: 1 C/cm ²	Redundant tracking and triggering
LHCb MUON UPGRADE CERN LS4	Hadron Collider (triggering)	μ-RWELL	Total area: $\sim 90 \text{ m}^2$ Single unit detector: From 0,4x0,3 m ² To 0,8x0,3 m ²	Max.rate:900 kHz/cm ² Spatial res.: ~ cm Time res.: ~ 3 ns Rad. Hard.: ~ 2 C/cm ²	About 600 detectors

Challenges: HL-LHC



Maintain standalone trigger and reconstruction, mitigation of efficiency loss due to aging of the current detectors can be met if:

the number of hits recorded is sufficiently large

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- spatial accuracy and the time resolution are very good.
- good momentum measurement for the rejection of unwanted soft muons, mis-measured as high p_t muons → prevent increase in p_t threshold





CMS Muon Spectrometer after LS3



A cross-section of the CMS experiment after the Phase II upgrades



The GEM upgrade: three new stations GE1/1, GE2/1 and ME0 based on the triple-GEM technology

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The RPC upgrade: two new stations RE3/1 and RE4/1 based on the improved-RPC technology



How GEMs will help



Till LS2, forward trigger for $|\eta| > 1.6$ relies entirely on the CSC system (ME1/1) strong B field

GEM detector in front of CSC can measure muon bending angle in magnetic field and add redundancy





maintain 15 GeV online threshold, keep < 5 kHz rate, high efficiency

What are the GEM





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Electrons entering the GEM holes will accelerate in the intense electric field (~80 kV/cm) and provoke the ionization of gas molecules, giving rise to an electron avalanche Multiplication: 1 e- input to > 1000e-output (as a function of gas and HV)





Masters of GEM

CERN's Printed Circuit Workshop













Michele Bianco

CERN Detector Seminar

20



Mass Production & QA/QC

CERN







The Plan: General Organization



- **Dist**ribution of the production in various sites:
- Share the effort with CMS GEM institutes
- Generate a large community of GEM experts
- Equip production sites with infrastructure, tooling and knowledge for GE2/1 and ME0 productions

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- → 2-years training program
- Using same procedure
- Using equivalent infrastructure
- All Quality Control deliverables validated by the production community







Knowledge transfer

GEM Foils Production

- Mecaro (KR) (new producer investigated between 2017 and 2019 – approved in Jan. 2020), GE2/1 GEM Foils (M2, M3, M6 and M7 types)
- Organized an in-depth internal review with KCMS representatives, Mecaro engineers, project management and Rui directly at the Korean factory



- Excellent experience with the Korean teams from Mecaro and Korea-CMS
 - Large team of experts, almost a constant presence at the factory for the foil validation
 - In-depth inspection and test of all foils in Korea before shipping to CERN for additional cross-check measurements



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GEM (GE1/1) Production Coordination



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Technical Coordination & Detector Integration

GE-1/1 SCs installation in negative end-cap

- ✓ Installation of all 36 super-chambers for the first end-cap completed in Oct. 2019
- Multiple installation windows from July 2019 to October 2019





GE-1/1 SCs installation in the positive end-cap

- ✓ Installation of all 36 super-chambers for the second end-cap completed in Sept. 2020
- Installation and commissioning phase delayed to the COVID-19 lockdown





CMS Event with muons in all muon subdetectors

CMS Experiment at the LHC, CERN Data recorded: 2022-Jul-19 18:12:29.295936 GMT Run / Event / LS: 355862 / 37961720 / 122

Invariant Mass $M\mu\mu = 91$ GeV

Hit in GEM 1/

Muon in CSC+GEM+RPC: pT=28.8 GeV

Muon in DT+RPC: pT=30.9 GeV







CMS Event with muons in all muon subdetectors

Invariant Mass $M\mu\mu = 91 \text{ GeV}$

CMS Experiment at the LHC, CERN Data recorded: 2022-Jul-19 18:12:49.162048 GMT Run / Event / LS: 355862 / 38856449 / 123

Muon in CSC+RPC: p_T=18.3 GeV

Hit in GEM

Muon in CSC+RPC: p_T=4.4 GeV (misses CSC in station 3 but RPC hit there)

Hit in GEM

Muon in DT+RPC: p_T=38.9 GeV







CMS Event with muons in all muon subdetectors





FCC Feasibility Study (FS) 2021-2025

LHC

Switzerland

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France

FCC 100 km circumference

Gaseous Tracking / Muon Detection @ Future Colliders: Drift Chamber → TPC → RPC → Micro-Pattern Gas Detectors

Primary choice for large-area coverage with low material-budget (+ dE/dx measurement)

1990's: Industrial advances in photolithography has favoured the invention of novel micro-structured gas amplification devices (MSGC, GEM, Micromegas, ...)

- Scaling up MPGD detectors, while preserving the typical properties of small prototypes, allowed their use in the LHC upgrades
 - → Many emerged from the R&D studies within the CERN-RD51 Collaboration
- Successful accomplishment of LHC upgrades will help to disseminate MPGD technologies even wider

RD51 extension (2019-2023): arXiv: 1806.09955



HL-LHC Upgrades: Tracking (ALICE TPC/GEM); Muon Systems: RPC, CSC, MDT, TGC, GEM, Micromegas;

Future Hadron Colliders: FCC-hh Muon System (MPGD - OK, particle rates are comparable with HL-LHC) Future Lepton Colliders: Tracking (FCC-ee / CepC - Drift Chambers; ILC / CePC - TPC with MPGD readout) Calorimetry (ILC, CepC – RPC or MPGD), Muon Systems (many gas det. are OK)

Future Election-Ion Collider: Tracking (GEM, μWELL; TPC/MPGD), RICH (THGEM), TRD (GEM)



What are the challenges met for LHC?



Design of high performance, high resolution and extreme radiation tolerant detectors

Long term integration complex and large size heterogeneous detector systems in harsh environments

Broad range of assembly, testing and qualifying capabilities, required to develop and commission new detector systems.

Extremely radiation tolerant detector technology	~10gray / year
Magnetic field tolerant detector technology	4T
Operational frequency resulting from particle collisions every 25nsec	40MHz
Number of sensors in the LHC	150 M



Designing stable carbon fibre structures







Expertise in the design, manufacture, installation and integration of stable, lightweight support structures based on Carbon Fibre Composite Materials,

Required to provide long lasting structural integrity and stability to the detectors while being exposed to high radiation and magnetic fields. Expertise and know-how in:

- Filament winding, hand layup and resin transfer moulding.
- Material characterisation.
- Sensor integration for structural health monitoring.
- Integration of electronics components.
- Design and integration of advanced thermal-management solutions (e.g. micro-cooling plates).
- Fittings Welding, soldering, gluing.



Thermal management using silicon microchannels





The volumetric power density of a LHC Pixel detector is approximately 100 W/dm3 - comparable to the most demanding high power electronics applications. To provide stable and precisely controlled thermal management, CERN experts have developed knowhow in the design and manufacture of ultra-thin microchannel cooling plates.

- Proven technology already adopted in two experiments at CERN
- Cooling up to 100s W/cm2 depending on design
- Down to 150um silicon
- Suitable for single or two-phase refrigerants
- No mismatch in coefficient of thermal expansion (CTE) between integrated circuits
- Significant expertise in the integration of microscale components, surface preparation, and bonding techniques
- Ongoing R&D on new microfabrication techniques



Cooling of integrated circuits, particularly where stable thermal management is needed, for example...

- Laboratory coolers
- Manufacturing of specialised components
- Data centres
- Know-how on designs for high power density cooling:
- → Increase performance and protect electronic equipment from thermal damage
- Ultra-compact, integrated cold plate/heat exchanger:
 - Reduce space requirements
- Know-how on interconnection of multiple devices:
 - → Large cooling surfaces possible (>300mm)



Designing scintillator based detectors





Scintillators are applied in high-energy physics to measure the energy of particles that are produced in particle physics experiments. Therefore, CERN developed highly specialized expertise and infrastructure for research and development of inorganic scintillation technologies for novel ionizing radiation detectors.

- Characterization of scintillation materials and detectors: thermalized benches for characterization of transmission, emission light yield and timing properties, single photon counting and coincidence time measurements, spectrophoto- and fluorimetry, streak camera, pulsed X-rays and irradiation facilities
- Monte Carlo simulation, including ray tracing of light transport and collection
- Nanocrystals metamaterials and nanophotonics



- Particle physics
- Medical imaging radiology and nuclear imaging
- Radiation protection
- Industrial applications non-destructive testing
- Complete and versatile scintillator research infrastructure

 Characterisation of components and full detector chain

- Simulation of complex detector systems
 - → Cost-efficient optimization
- Broad knowledge in detector materials
 - → Adaptable to many fields of application



High resolution silicon detectors





The LHC equipment is exposed to high levels of radiation. Therefore, CERN has developed unique expertise in design and integration of high performance and extreme radiation tolerant ASICs. Broad range of testing and qualifying capability for radiation hardness of ASICs. Pushing the limits of mixed-mode circuit design for large detector systems.

- Design of hybrid pixel detectors (Medipix family chips)
- Design of monolithic detectors (ALPIDE, MALTA)
- Design and integration in complex systems including Front-End electronics, mechanical structure and cooling devices



- Medical imaging
- Hadron-therapy beam monitoring
- X rays imaging
- Non-destructive testing
- Particle track reconstruction for Aerospace
- Colour Xray imaging

→ Detect various components

- High resolution, able to count single photons
 - \rightarrow Designed for particle tracking
- Can be used on wide range of detection devices
 - \rightarrow Very broad applicability



High resolution silicon detectors

Gadolinium





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expertise and extre testing a of ASICs. design fo

- Desig ۲ chips
- Desig

cooling devices

Desig Water Calcium Golo Front-End electronics, mechanical structure and



Medical imaging



- Can be used on wide range of detection devices
 - \rightarrow Very broad applicability



A pileup of 1000 proton–proton collisions per bunch-crossing, highly boosted objects and radiation levels up to 1018 hadrons per cm2 are just some of the challenges in extracting physics from a next-generation hadron collider to follow the LHC.



The layout of the FCC-hh reference detector, with a diameter of 20 m and length of 50 m, comparable to the dimensions of the ATLAS detector but much heavier. The central detector houses the tracking, electromagnetic calorimetry and hadron calorimetry inside a 4 T solenoid with a free bore diameter of 10 m (purple). The forward parts are displaced by 10 m from the interaction point, with two forward magnet coils (solenoids shown) providing the required bending power. The muon system is placed outside the magnet coils Source: CERN Yellow Reports Monographs CERN-2022-002

Towards Large Area in Fast Timing GASEOUS DETECTORS

Multi-Gap Resistive Plate Chambers (MRPC):



Gaseous Tracking Systems @ Future Colliders

Experiment / Timescale	Application Domain	Gas Detector Technology	Total detector size / Single module size	Operation Characteristics / Performance	Special Requirements/ Remarks
ILC TPC DETECTOR: STARTt: > 2035	e+e- Collider Tracking + dE/dx	MM, GEM (pads) InGrid (pixels)	Total area: ~ 20 m ² Single unit detect: ~ 400 cm ² (pads) ~ 130 cm ² (pixels)	Max. rate: < 1 kHz Spatial res.: <150µm Time res.: ~ 15 ns dE/dx: 5 %	Si + TPC Momentum resolution : dp/p < 9*10 ⁻⁵ 1/GeV Power-pulsing
CEPC TPC DETECTOR START: > 2030	e+e- Collider Tracking + dE/dx	MM, GEM (pads) InGrid (pixels)	Total area: ~ 2x10 m ² Single unit detect: up to 0.04 m ²	Max.rate:>100 kHz/cm ² Spatial res.: ~100µm Time res.: ~ 100 ns dE/dx: <5%	- Higgs run - Z pole run - Continues readout - Low IBF and dE/dx
FCC-ee and/or CEPC IDEA CENTRAL TRACKER START: >2030	e+e- Collider Tracking/ Triggering	He based Drift Chamber	Total volume: 50 m ³ Single unit detect: (12 m ² X 4 m)	Max. rate: < 25 kHz/cm ² Spatial res.: <100 µm Time res.: 1 ns Rad. Hard.: NA	Particle sepration with cluster counting at 2% level
SUPER-CHARM TAU FACTORY START: > 2025	e+e- Collider Main Tracker	Drift Chamber	Total volume: ~ 3.6 m ³	Max. rate: 1 kHz/cm ² Spatial res.: ~100 μm Time res.: ~ 100 ns Rad. Hard.: ~ 1 C/cm	
SUPER-CHARM TAU FACTORY START: > 2025	e+e- Collider Inner Tracker	Inner Tracker / (cylindrical μRWELL, or TPC / MPDG read.	Total area: ~ 2 - 4 m ² Single unit detect: 0.5 m ²	Max. rate: 50-100 kHz/cm ² Spatial res.: ~<100 μm Time res.: ~ 5 -10 ns Rad. Hard.: ~ 0.1-1 C/cm ²	Challenging mechanics & mat. budget < 1% X0
ELECTRON-ION COLLIDER (EIC) START: > 2025	Electron-Ion Collider Tracking	Barrel: cylindrical MM, μRWELL Endcap: GEM, MM, μRWELL	Total area: ~ 25 m ²	Luminosity (e-p): 10 ³³ Spatial res.: ~ 50- 100 um Max. rate: ~ kHz/cm ²	Barrel technical challenges: low mass, large area Endcap: moderate technical challenges



And the cycle continues....





Mechanical Engineering